	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	3749	(257/686,698,700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
2	BRS	L2	583	multi adj layer adj wiring adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
3	BRS	L3	292	(semiconductor chip or chip) and (multi adj layer adj wiring adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
4	BRS	L4	684657	(semiconductor near2 (chip or element or device or dice or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
5	BRS	L5	18681	(multi-layer$6 or multilayer$6) near2 board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	117	1 and 4 and 5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23
7	IS&R	L9	1192	(257/698).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31
8	BRS	L14	116	2 same (semiconductor adj element or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:47
9	BRS	L15	794	8 and (@ad<20000113)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:48
10	IS&R	L16	1415	(257/700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 17:43

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	IS&R	L17	1150	(257/734).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 18:24
12	IS&R	L18	168	(257/736).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 18:44
13	IS&R	L19	159	(257/748).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 18:59
14	IS&R	L20	1431	(257/686).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 19:43

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	3749	(257/686,698,700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
2	BRS	L2	583	multi adj layer adj wiring adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
3	BRS	L3	292	(semiconductor chip or chip) and (multi adj layer adj wiring adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
4	BRS	L4	684657	(semiconductor near2 (chip or element or device or dice or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
5	BRS	L5	18681	(multi-layer$6 or multilayer$6) near2 board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	117	1 and 4 and 5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23
7	IS&R	L9	1192	(257/698).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31
8	IS&R	L10	1415	(257/700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31
9	IS&R	L11	1150	(257/734).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31
10	IS&R	L12	168	(257/736).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	IS&R	L13	159	(257/748).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:31
12	IS&R	L8	1431	(257/686).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:41
13	BRS	L14	116	2 same (semiconductor adj element or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:47
14	BRS	L15	794	8 and (@ad<20000113)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:48

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	3749	(257/686,698,700).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
2	BRS	L2	583	multi adj layer adj wiring adj board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:21
3	BRS	L3	292	(semiconductor chip or chip) and (multi adj layer adj wiring adj board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
4	BRS	L4	684657	(semiconductor near2 (chip or element or device or dice or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:22
5	BRS	L5	18681	(multi-layer$6 or multilayer$6) near2 board	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	117	1 and 4 and 5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/20 16:23

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L1	159	(257/748).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/21 11:51
2	IS&R	L2	168	(257/736).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/21 12:05
3	IS&R	L3	1192	(257/698).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/21 12:59
4	BRS	L5	852	3 and (@ad<20000113)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/21 13:00